

update

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(substrate) and (remove insulation)	0

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L46

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 result set

DB=PGPB,USPT,USOC,EPAB,JPAB,DWPI,TDBD; PLUR=YES; OP=ADJ

L46 (substrate) and (remove insulation) 0 L46

L45 L44 and "insulation" 11 L45

L44 (contact thermocouple) and (substrate) 126 L44

DB=PGPB; PLUR=YES; OP=ADJ

L43 L1 and "substrate" 1 L43

DB=PGPB,USPT,USOC,EPAB,JPAB,DWPI,TDBD; PLUR=YES; OP=ADJ

L42 L41 and "semiconductor wafer" 23 L42

L41 thin film thermocouple 227 L41

DB=PGPB; PLUR=YES; OP=ADJ

L40 L1 and "extends" 1 L40

L39 L1 and "extends beyond an edge" 0 L39

DB=PGPB,USPT,USOC,EPAB,JPAB,DWPI,TDBD; PLUR=YES; OP=ADJ

L38 junction on substrate 0 L38

L37 L20 and "thin film thermocouple" 42 L37

<u>L36</u>	L35 and "thermocouple"	83	<u>L36</u>
<u>L35</u>	measure substrate temperature	149	<u>L35</u>
<u>L34</u>	junction on bare substrate	0	<u>L34</u>
<u>L33</u>	temperature instrumented	12	<u>L33</u>
<i>DB=USPT; PLUR=YES; OP=ADJ</i>			
<u>L32</u>	6472240.pn.	1	<u>L32</u>
<i>DB=PGPB,USPT,USOC,EPAB,JPAB,DWPI; PLUR=YES; OP=ADJ</i>			
<u>L31</u>	temperature instrumented semiconductor	3	<u>L31</u>
<i>DB=PGPB; PLUR=YES; OP=ADJ</i>			
<u>L30</u>	temperature instrumented semiconductor	1	<u>L30</u>
<i>DB=USPT; PLUR=YES; OP=ADJ</i>			
<u>L29</u>	L20 and "Laof"	0	<u>L29</u>
<i>DB=PGPB; PLUR=YES; OP=ADJ</i>			
<u>L28</u>	L27 and "thermocouple"	3	<u>L28</u>
<u>L27</u>	schuh	132	<u>L27</u>
<i>DB=PGPB,USPT,USOC,EPAB,JPAB,DWPI,TDBD; PLUR=YES; OP=ADJ</i>			
<u>L26</u>	temperature indicating wafer	2	<u>L26</u>
<u>L25</u>	temperature calibrating wafer	1	<u>L25</u>
<u>L24</u>	L21 and "SenseArray"	0	<u>L24</u>
<u>L23</u>	L21 and "thermocouple"	224	<u>L23</u>
<u>L22</u>	L21 and "hot junction"	1	<u>L22</u>
<u>L21</u>	L20 and "temperature wafer"	350	<u>L21</u>
<u>L20</u>	374/\$	33203	<u>L20</u>
<u>L19</u>	temperature wafer	6691	<u>L19</u>
<u>L18</u>	hot junction formed on substrate	0	<u>L18</u>
<u>L17</u>	L16 and "insulation"	34	<u>L17</u>
<u>L16</u>	forming hot junction	85	<u>L16</u>
<u>L15</u>	L12 and "hot junction"	18	<u>L15</u>
<u>L14</u>	L12 and "hot junction"	18	<u>L14</u>
<u>L13</u>	L12 and "substrate"	13	<u>L13</u>
<u>L12</u>	374/180	149	<u>L12</u>
<u>L11</u>	film extends beyond substrate	2	<u>L11</u>
<i>DB=PGPB; PLUR=YES; OP=ADJ</i>			
<u>L10</u>	L1 and "stretch"	0	<u>L10</u>
<u>L9</u>	L1 and "tension"	0	<u>L9</u>
<u>L8</u>	L1 and "compressive"	0	<u>L8</u>
<u>L7</u>	L1 and "compression"	0	<u>L7</u>
<u>L6</u>	L1 and "tensile"	0	<u>L6</u>
<i>DB=PGPB,USPT,USOC,EPAB,JPAB,DWPI,TDBD; PLUR=YES; OP=ADJ</i>			
<u>L5</u>	L4 and "thin film"	50	<u>L5</u>
<u>L4</u>	positive strain	803	<u>L4</u>

DB=PGPB; PLUR=YES; OP=ADJ

L3 L2 and "positive"

0 L3

L2 L1 and "0.006"

1 L2

L1 20040101022

1 L1

END OF SEARCH HISTORY